Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

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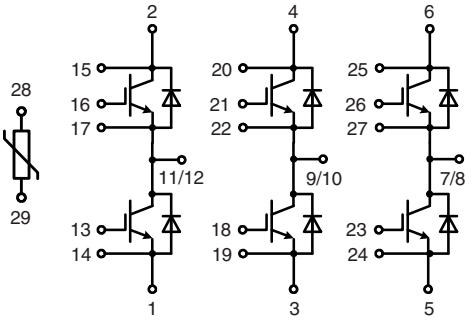
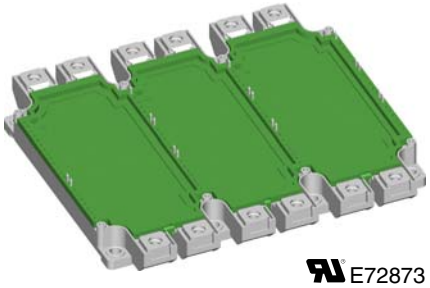
IGBT Modules
Sixpack

I_{C60} = 475 A
V_{CES} = 1700 V
$V_{CE(sat)\ typ}$ = 2.25 V

Preliminary data





E72873

See outline drawing for pin arrangement

Features
- NPT³ IGBT technology
- low saturation voltage
- low switching losses
- square RBSOA, no latch up
- high short circuit capability
- positive temperature coefficient for easy parallelling
- MOS input, voltage controlled
- ultra fast free wheeling diodes
- solderable pins for PCB mounting
- package with copper base plate

Advantages
- space savings
- reduced protection circuits
- package designed for wave soldering

Typical Applications
- AC motor control
- AC servo and robot drives
- power supplies

Recommended replacement: MWI 450-17T9

IGBTs

Symbol	Conditions	Maximum Ratings	
V_{CES}	T_{VJ} = 25°C to 125°C	1700	V
V_{GES}		± 20	V
I_{C25}	T_C = 25°C	580	A
I_{C60}	T_C = 60°C	475	A
I_{C80}	T_C = 80°C	405	A
RBSOA	R_G = 3.3 Ω; T_{VJ} = 125°C Clamped inductive load; L = 100 µH	I_{CM} = 750 $V_{CEK} \le V_{CES}$	A
t_{SC} (SCSOA)	V_{CE} = 1200 V; V_{GE} = ±15 V; R_G = 3.3 Ω; T_{VJ} = 125°C; non-repetitive; $V_{CEmax} \le V_{CES}$	10	µs
P_{tot}	T_C = 25°C	2.2	kW

Symbol	Conditions	Characteristic Values (T_{VJ} = 25°C, unless otherwise specified) min.	typ.	max.	
$V_{CE(sat)}$	I_C = 450 A; V_{GE} = 15 V; T_{VJ} = 25°C		2.25	2.65	V
	T_{VJ} = 125°C		2.65	3.0	V
$V_{GE(th)}$	I_C = 30 mA; V_{GE} = V_{CE}	5		7	V
I_{CES}	V_{CE} = V_{CES}; V_{GE} = 0 V; T_{VJ} = 25°C			1	mA
	T_{VJ} = 125°C		9	26	mA
I_{GES}	V_{CE} = 0 V; V_{GE} = ± 20 V			1.5	µA
$t_{d(on)}$	Inductive load, T_{VJ} = 125°C		100		ns
t_r	V_{CE} = 900 V; I_C = 450 A		90		ns
$t_{d(off)}$	V_{GE} = ±15 V; R_G = 3.3 Ω		470		ns
t_f			400		ns
E_{on}			90		mJ
E_{off}			90		mJ
C_{ies}	V_{CE} = 25 V; V_{GE} = 0 V; f = 1 MHz		33		nF
Q_{Gon}	V_{CE} = 900 V; V_{GE} = 15 V; I_C = 300 A		2.6		µC
R_{thJC}				0.057	K/W

IXYS reserves the right to change limits, test conditions and dimensions.

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Diodes

Symbol	Conditions	Maximum Ratings	
I_{F80}	T_C = 80°C	450	A
I_{FRM}	t_p = 1 ms	900	A
I^2t	T_{VJ} = 125°C; t = 10 ms; V_R = 0 V	35000	A^2s

Symbol	Conditions	Characteristic Values min.	typ.	max.	
V_F	I_F = 450 A; V_{GE} = 0 V; T_{VJ} = 25°C			2.2	V
I_{RM}	I_F = 450 A; di_F/dt = 3500 A/µs; T_{VJ} = 125°C; V_R = 1200 V		400		A
R_{thJC}			0.075		K/W

Temperature Sensor NTC

Symbol	Conditions	Characteristic Values min.	typ.	max.	
R_{25}	T = 25°C	4.75	5.0	5.25	kΩ
$B_{25/50}$			3375		K

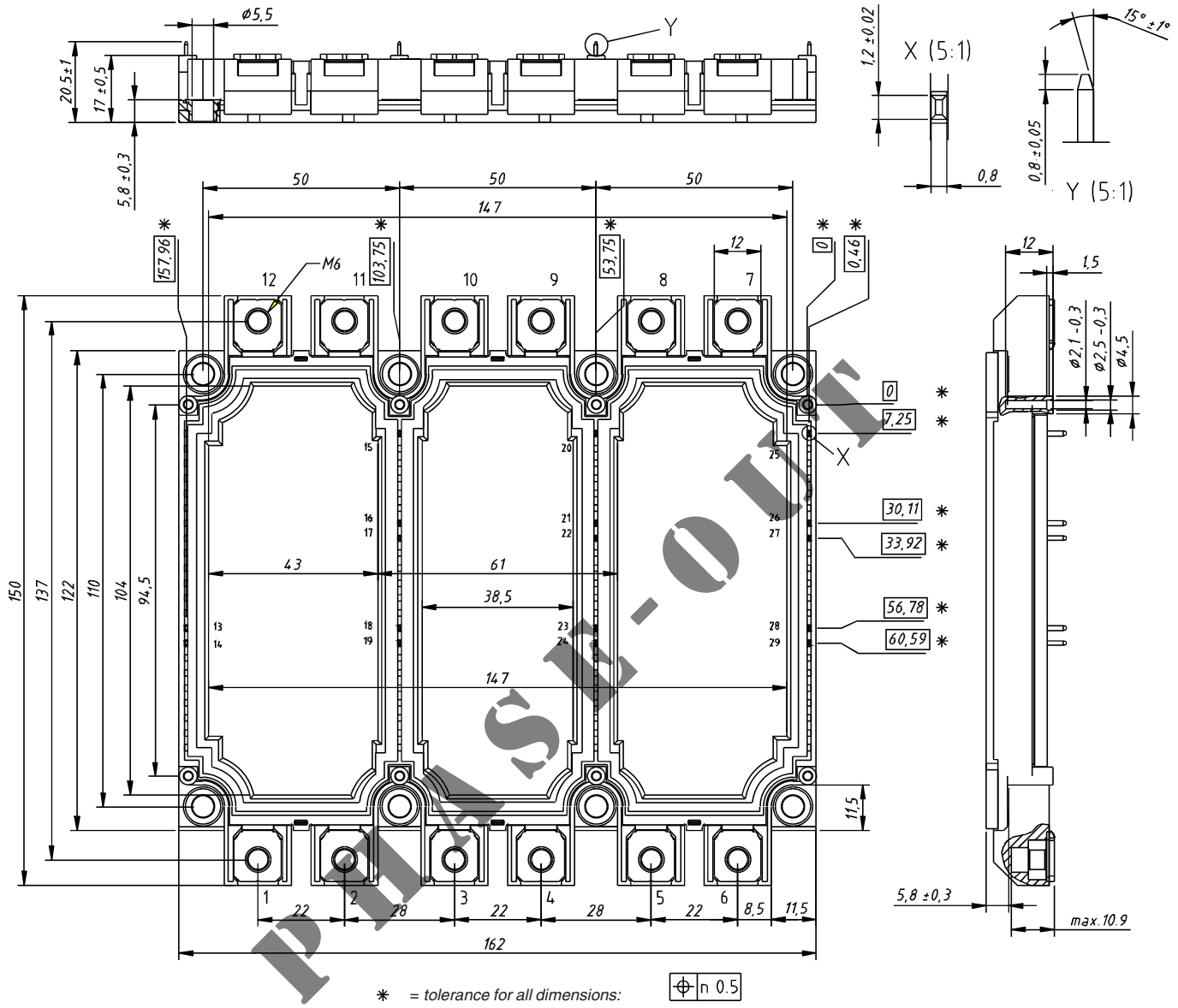
Module

Symbol	Conditions	Maximum Ratings	
T_{VJ}	operating	-40...+125	°C
T_{JM}		+150	°C
T_{stg}		-40...+125	°C
V_{ISOL}	$I_{ISOL} \leq$ 1 mA; 50/60 Hz	3400	V~
M_d	Mounting torque (M5)	3 - 6	Nm
	Terminal connection torque (M6)	3 - 6	Nm

Symbol	Conditions	Characteristic Values min.	typ.	max.	
$R_{term-chip}$ *)	Resistance terminal to chip		0.55		mΩ
d_S	Creepage distance on surface	12.7			mm
d_A	Strike distance in air	10			mm
R_{thCH}	with heatsink compound		0.01		K/W
Weight			900		g

*) $V = V_{CE(sat)} + 2x\ R_{term-chip} \cdot I_C$ resp. $V = V_F + 2x\ R_{term-chip} \cdot I_F$

Dimensions in mm (1 mm = 0.0394")



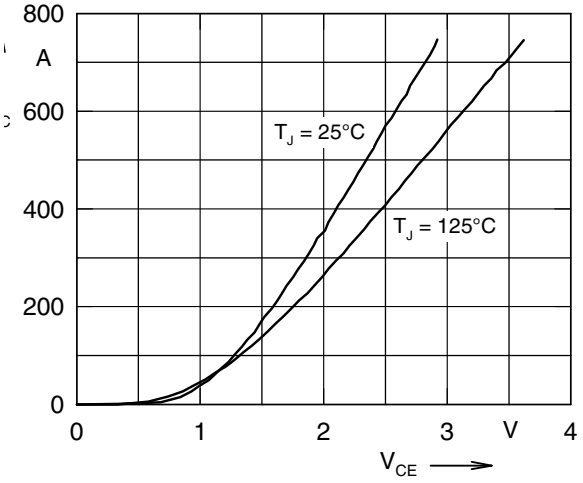


Fig. 1 Typ. output characteristics

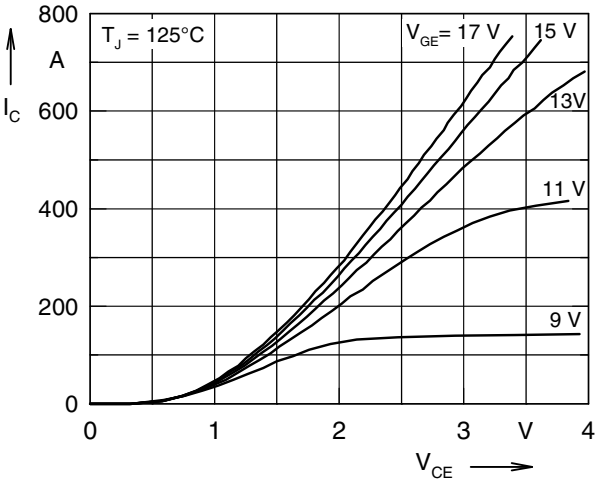


Fig. 2 Typ. output characteristics